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Amir Said
Onur G. Guleryuz
Robert L. Stevenson
Editors

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Contents

v *Conference Committee*

SESSION 1

8666 01 **Fairness issues in resource allocation schemes for wireless visual sensor networks** [8666-1]
K. Pandremmenou, L. P. Kondi, K. E. Parsopoulos, Univ. of Ioannina (Greece)

8666 02 **Discussion on information theoretic and simulation analysis of linear shift-invariant edge detection operators** [8666-2]
B. Jiang, National Institute of Aerospace (United States)

SESSION 2

8666 04 **Inter-layer motion field mapping for the scalable extension of HEVC (Invited Paper)** [8666-5]
X. Xiu, Y. Ye, Y. He, Y. He, InterDigital Communications, LLC (United States)

8666 05 **An HEVC extension for spatial and quality scalable video coding (Invited Paper)** [8666-6]
T. Hinz, P. Helle, H. Lakshman, M. Siekmann, J. Stegemann, H. Schwarz, D. Marpe, Fraunhofer Institute for Telecommunications, Heinrich Hertz Institute (Germany); T. Wiegand, Fraunhofer Institute for Telecommunications, Heinrich Hertz Institute (Germany) and Berlin Institute of Technology (Germany)

8666 06 **Towards a next generation open-source video codec (Invited Paper)** [8666-7]
J. Bankoski, R. S. Bultje, A. Grange, Q. Gu, J. Han, J. Koleszar, D. Mukherjee, P. Wilkins, Y. Xu, Google, Inc. (United States)

SESSION 3

8666 07 **Scalable extensions of HEVC for next generation services (Invited Paper)** [8666-8]
K. Misra, A. Segall, J. Zhao, S.-H. Kim, Sharp Labs. of America Inc. (United States)

8666 08 **An improved hypothetical reference decoder for HEVC (Invited Paper)** [8666-9]
S. Deshpande, Sharp Labs. of America Inc. (United States); M. M. Hannuksela, Nokia Research Ctr. (Finland); K. Kazui, Fujitsu Labs., Ltd. (Japan); T. Schierl, Fraunhofer Institute for Telecommunications, Heinrich Hertz Institute (Germany)

8666 09 **On lossless coding for HEVC (Invited Paper)** [8666-10]
W. Gao, Huawei Media Lab. (United States); M. Jiang, Real Communications Inc. (United States); H. Yu, Huawei Media Lab. (United States)

8666 0A **Edge adaptive intra field de-interlacing of video images** [8666-11]
V. Lachine, G. Smith, L. Lee, Qualcomm Canada Inc. (Canada)

- 8666 OB **On the efficiency of image completion methods for intra prediction in video coding with large block structures** [8666-12]
D. Doshkov, O. Jottrand, Fraunhofer Institute for Telecommunications, Heinrich Hertz Institute (Germany); T. Wiegand, Fraunhofer Institute for Telecommunications, Heinrich Hertz Institute (Germany) and Berlin Institute of Technology (Germany); P. Nadjiki-Nya, Fraunhofer Institute for Telecommunications, Heinrich Hertz Institute (Germany)

SESSION 4

- 8666 OC **Depth-layer-based multiview image synthesis and coding for interactive z- and x-dimension view switching** [8666-13]
Y. Mao, The Graduate Univ. for Advanced Studies (Japan); G. Cheung, Y. Ji, National Institute of Informatics (Japan)
- 8666 OD **Wyner-Ziv coding of depth maps exploiting color motion information** [8666-14]
M. Salmistraro, M. Zamarin, S. Forchhammer, Technical Univ. of Denmark (Denmark)
- 8666 OE **Multimodal image registration by iteratively searching keypoint correspondences** [8666-15]
Y. Li, R. Stevenson, Univ. of Notre Dame (United States)
- 8666 OF **A spatially varying PSF model for Seidel aberrations and defocus** [8666-16]
J. D. Simpkins, R. L. Stevenson, Univ. of Notre Dame (United States)

SESSION 5

- 8666 OH **Cubic-panorama image dataset analysis for storage and transmission** [8666-18]
S. Salehi, E. Dubois, Univ. of Ottawa (Canada)
- 8666 OI **Efficient streaming of stereoscopic depth-based 3D videos** [8666-19]
D. Temel, M. Aabed, Georgia Institute of Technology (United States); M. Solh, Texas Instruments Inc. (United States); G. AlRegib, Georgia Institute of Technology (United States)

INTERACTIVE PAPER SESSION

- 8666 OJ **Block-layer bit allocation for quality constrained video encoding based on constant perceptual quality** [8666-20]
C. Wang, X. Mou, W. Hong, Xi'an Jiaotong Univ. (China); L. Zhang, The Hong Kong Polytechnic Univ. (Hong Kong, China)
- 8666 OK **A bilateral hole filling algorithm for time-of-flight depth camera** [8666-21]
S.-W. Jung, Samsung Advanced Institute of Technology (Korea, Republic of)

Author Index

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Session 4

Robert L. Stevenson, University of Notre Dame (United States)

Session 5

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